



Material Content Data Sheet



Sales Product Name	TLF51801ELV			Issued	22. July 2019			
MA#	MA001033070							
Package	PG-SSOP-14-3			Weight*	83.01 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.743	2.10	2.10	20997	20997
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		415	
	non noble metal	iron	7439-89-6	0.689	0.83		8301	
wire	non noble metal	copper	7440-50-8	27.978	33.71	34.59	337057	345877
	noble metal	gold	7440-57-5	0.210	0.25	0.25	2536	2536
	encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1204
encapsulation	plastics	epoxy resin	-	4.596	5.54		55369	
	inorganic material	silicondioxide	60676-86-0	45.260	54.53	60.19	545261	601834
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11760	11760
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9248	9248
glue	plastics	epoxy resin	-	0.161	0.19		1937	
	noble metal	silver	7440-22-4	0.482	0.58	0.77	5811	7748
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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